

11/20/02 1725

TRANSMITTAL OF INFORMATION DISCLOSURE STATEMENT  
(Under 37 CFR 1.97(b) or 1.97(c)) O I P E

Docket No.  
15574

In Re Application Of: Hiroshi SAKAI, et al.



Serial No.  
10/063,915

Filing Date  
May 23, 2002

Examiner  
Kevin L. McHenry

Group Art Unit  
1725

Title: SOLDER PASTE PRINTING METHOD AND APPARATUS FOR PRINTING  
SOLDER PASTE ON A BOARD ON WHICH WIRING PATTERNS ARE FORMED

Address to:  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**37 CFR 1.97(b)**

- The Information Disclosure Statement submitted herewith is being filed within three months of the filing of a national application other than a continued prosecution application under 37 CFR 1.53(d); within three months of the date of entry of the national stage as set forth in 37 CFR 1.491 in an international application; before the mailing of a first Office Action on the merits, or before the mailing of a first Office Action after the filing of a request for continued examination under 37 CFR 1.114.

**37 CFR 1.97(c)**

- The Information Disclosure Statement submitted herewith is being filed after the period specified in 37 CFR 1.97(b), provided that the Information Disclosure Statement is filed before the mailing date of a Final Action under 37 CFR 1.113, a Notice of Allowance under 37 CFR 1.311, or an Action that otherwise closes prosecution in the application, and is accompanied by one of:

the statement specified in 37 CFR 1.97(e);

OR

the fee set forth in 37 CFR 1.17(p).

**TRANSMITTAL OF INFORMATION DISCLOSURE STATEMENT**  
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**Payment of Fee**

(Only complete if Applicant elects to pay the fee set forth in 37 CFR 1.17(p))

A check in the amount of \_\_\_\_\_ is attached.

The Director is hereby authorized to charge and credit Deposit Account No. 19-1013/SSMP as described below.

Charge the amount of \_\_\_\_\_

Credit any overpayment.

Charge any additional fee required.

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I certify that this document and authorization to charge deposit account is being facsimile transmitted to the United States Patent and Trademark Office (F:

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I certify that this document and fee is being deposited on October 9, 2003 with the U.S. Postal Service as first class mail under 37 C.F.R. 1.8 and is addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

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Signature

\_\_\_\_\_  
Paul J. Esatto, Jr.

\_\_\_\_\_  
Typed or Printed Name

\*This certificate may only be used if paying by deposit account.

\_\_\_\_\_  
Signature

Dated: October 9, 2003

Paul J. Esatto, Jr.

Registration No. 30,749

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PJE:AVS:jap

CC:



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Hiroshi SAKAI, et al. Examiner: Kevin L. McHenry  
Serial No.: 10/063,915 Art Unit: 1725  
Filed: May 23, 2002 Docket: 15574  
For: SOLDER PASTE PRINTING METHOD  
AND APPARATUS FOR PRINTING  
SOLDER PASTE ON A BOARD ON WHICH  
WIRING PATTERNS ARE FORMED Dated: October 9, 2003

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

INFORMATION DISCLOSURE STATEMENT

Sir:

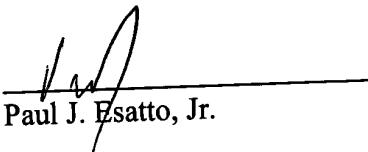
In accordance with 37 C.F.R §§1.97 and 1.98, it is requested that the following references, which are also listed on the attached Form PTO-1449, be made of record in the above-identified case.

1. Japanese Laid-Open Patent Application No. 5-96842, dated April 20, 1993;
2. Japanese Laid-Open Patent Application No. 11-1325, dated January 6, 1999;

CERTIFICATE OF MAILING UNDER 37 C.F.R. §1.8(a)

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on October 9, 2003.

Dated: October 9, 2003

  
Paul J. Esatto, Jr.

3. Japanese Laid-Open Patent Application No. 9-62146, dated March 7, 1997;
4. Japanese Laid-Open Patent Application No. 11-347789, dated December 21, 1999; and
5. Japanese Laid-Open Patent Application No. 11-300492, dated November 2, 1999.

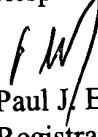
The references listed above were cited in an Official Action dated August 26, 2003 received from the Japanese Patent Office. Applicants are submitting copies of the above references, together with an English translation of the Examiner's comments regarding the references from the Official Action. Please note that the other references cited in the Official Action, namely, Japanese Laid-Open Patent Application No. H10-217425, dated August 18, 1998 and Japanese Laid-Open Patent Application No. 2001-47601, dated February 20, 2001, were previously submitted in applicants' Information Disclosure Statement dated August 7, 2003. The relevance of the references is described in the Official Action.

In compliance with the requirements of 37 C.F.R. §1.98(a)(3), as a concise statement of relevance, as it is presently understood by the individual designated in 37 C.F.R. §1.56(c) most knowledgeable about the content of the information, the undersigned attorney of record submits a translation of portions of an official action by a foreign examiner in which the references were cited. The relevance to the pending U.S. patent application is that the references were cited in a foreign patent application on the same subject matter. However, no independent analysis of the references, the accuracy of the statement of the foreign examiner or the claims of the foreign application under the laws of that country or the United States relative to the subject matter claimed in the present application has been made; the present understanding of the

contents thereof by the undersigned being based on the translation of the foreign examiner's comments submitted herewith.

Inasmuch as this Information Disclosure Statement is being submitted in accordance with the schedule set out in 37 C.F.R. §1.97(c), the statement is enclosed.

Respectfully submitted,

  
Paul J. Esatto, Jr.  
Registration No. 30,749

Scully, Scott, Murphy & Presser  
400 Garden City Plaza  
Garden City, New York 11530  
(516) 742-4343

PJE:AVS:jap



**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**Applicants:** Hiroshi SAKAI, et al.

**Examiner:** Kevin L. McHenry

**Serial No.:** 10/063,915

**Group:** 1725

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**Dated:** October 9, 2003

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Alexandria, VA 22313-1450

**STATEMENT PURSUANT**  
**TO 37 C.F.R. § 1.97(c)(1) and (e)(1)**

Sir:

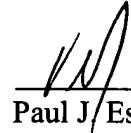
I hereby state that each item of information contained in this Information Disclosure Statement was first cited in any communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of this Information Disclosure Statement.

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**CERTIFICATE OF MAILING UNDER 37 C.F.R. §1.8(a)**

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on October 9, 2003.

Dated: October 9, 2003

  
\_\_\_\_\_  
Paul J. Esatto, Jr.

Accordingly, it is respectfully requested that the accompanying Information Disclosure Statement be considered with respect to the above-identified application.

Respectfully submitted,

  
Paul J. Esatto, Jr.  
Registration No. 30,749

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